

ABSTRACT

To provide a method of manufacturing an electronic component, in which occurrence of voids and degradation of characteristics with time at the resin-sealed part negligibly occur, and cost reduction can be attained, a sealing step for sealing SAW elements 2 by a sealing resin part 4 originating from a resin film 12 is provided by putting the SAW elements 2 mounted on a collective mounting substrate 11 and the resin film 12 in a bag 13 with a gas-barrier property, and causing the resin film 12 to infiltrate between the SAW elements 2 mounted on the reduce-pressured-packed collective mounting substrate 11 to be hermetically sealed, by means of the pressure difference between the inside and the outside of the bag 13.